



100V COMPLEMENTARY ENHANCEMENT MODE MOSFET H-BRIDGE

Product Summary

Device	BVDSS	Rds(on) Max	I _D T _A = +25°C
Q1 & Q4 100V	160mΩ @ V _{GS} = 10V	2.9A	
	1000	$200 \text{m}\Omega$ @ $V_{GS} = 4.5 \text{V}$	2.6A
03 8 03 4001/		250mΩ @ V _{GS} = -10V	-2.3A
Q2 & Q3	-100V	$300 \text{m}\Omega$ @ V _{GS} = -4.5V	-2.1A

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

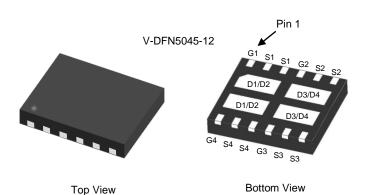
• High-efficiency bridge rectifiers

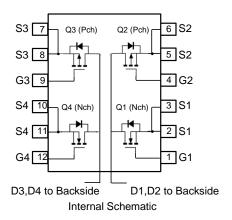
Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Package: V-DFN5045-12
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 € €
- Weight: 0.056 grams (Approximate)





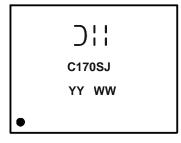
Ordering Information (Note 4)

Part Number	Paakaga	Tape Width	Packing	
Part Number	Package	rape widii	Qty.	Carrier
DMHC10H170SFJ-13	V-DFN5045-12	12mm	3,000	Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Dil = Manufacturer's Marking C170SJ = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 22 = 2022) WW = Week Code (01 to 53)



Maximum Ratings Q1 & Q4 N-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	100	V	
Gate-Source Voltage	Vgss	±20	V	
Continuous Drain Current (Note 5) V _{GS} = 10V Steady $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$		ID	2.9 2.3	А
Maximum Body Diode Forward Current (Note 5)	Is	2.5	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	13	Α	

Maximum Ratings Q2 & Q3 P-Channel (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	-100	V		
Gate-Source Voltage	Vgss	±20	V		
Continuous Drain Current (Note 5) Vcs = -10V		T _A = +25°C T _A = +70°C	lo	-2.3 -1.9	А
Maximum Body Diode Forward Current (Note 5)	ls	-2.3	A		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	IDM	-11	Α		

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	2.1	W
Thermal Resistance, Junction to Ambient (Note 5)	Reja	60	°C/W
Thermal Resistance, Junction to Case (Note 5)	Rejc	6	C/VV
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Note: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.



Electrical Characteristics Q1 & Q4 N-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BVDSS	100		_	٧	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	1	_	1	μΑ	$V_{DS} = 80V, V_{GS} = 0V$
Gate-Source Leakage	Igss	I		±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(TH)}	1.0	2.0	3.0	٧	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
Static Drain-Source On-Resistance	Dagger	I	111	160	mΩ	$V_{GS} = 10V, I_D = 5A$
Static Drain-Source On-Resistance	RDS(ON)	1	121	200	11122	$V_{GS} = 4.5V, I_D = 5A$
Diode Forward Voltage	VsD	_	0.9	1.0	V	V _G S = 0V, I _S = 10A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	Ciss	I	1,167	_		
Output Capacitance	Coss		36	_	pF	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1.0MHz$
Reverse Transfer Capacitance	Crss	1	25	_		
Gate Resistance	Rg		1.3	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$
Total Gate Charge (V _{GS} = 4.5V)	Qg	l	4.9	_		
Total Gate Charge (V _{GS} = 10V)	Qg		9.7	_	nC	\/ 00\/ I- 40.0A
Gate-Source Charge	Qgs	_	2.0	_	nc	$V_{DS} = 80V, I_{D} = 12.8A$
Gate-Drain Charge	Q_{gd}	_	2.0	_		
Turn-On Delay Time	td(ON)	_	10.5	_		
Turn-On Rise Time	t _R	_	11.1	_		V 50V B 050 L 40.04
Turn-Off Delay Time	tD(OFF)	_	42.6	_	ns	$V_{DD} = 50V, R_G = 25\Omega, I_D = 12.8A$
Turn-Off Fall Time	t _F	_	12.8	_		
Body Diode Reverse Recovery Time	t _{RR}	_	30.3	_	ns	$V_{GS} = 0V$, $I_S = 12.8A$, $dI/dt = 100A/\mu s$
Body Diode Reverse Recovery Charge	Q _{RR}		35.2	_	nC	V _G S = 0V, I _S = 12.8A, dI/dt = 100A/µs

Electrical Characteristics Q2 & Q3 P-Channel (@TA = +25°C, unless otherwise specified.)

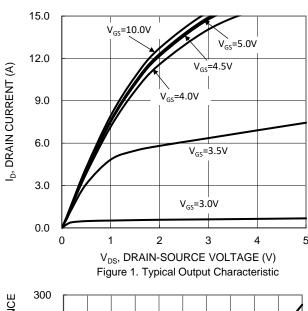
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	-100	_	_	V	Vgs = 0V, ID = -250µA
Zero Gate Voltage Drain Current	IDSS	_	_	1	μA	V _{DS} = -80V, V _{GS} = 0V
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	Vgs(TH)	-1.0	-1.6	-3.0	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	D	_	191	250	mΩ	V _{GS} = -10V, I _D = -5A
Static Drain-Source On-Resistance	R _{DS(ON)}	_	213	300	11122	Vgs = -4.5V, ID =-5A
Diode Forward Voltage	VsD	_	-0.9	-1.2	V	V _G S = 0V, I _S = -5A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	Ciss	1	1,239			
Output Capacitance	Coss	_	42	_	pF	$V_{DS} = -25V$, $V_{GS} = 0V$, $f = 1.0MHz$
Reverse Transfer Capacitance	Crss	_	28	_		
Gate Resistance	R_g	_	13	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	8.4	_		
Total Gate Charge (V _{GS} = -10V)	Qg	_	17.5	_	nC	V _{DS} = -60V. I _D = -5A
Gate-Source Charge	Q _{gs}	_	2.8	_	110	VDS = -60 V, ID = -5A
Gate-Drain Charge	Qgd	_	3.2	_		
Turn-On Delay Time	tD(ON)	_	9.1	_		
Turn-On Rise Time	t _R	_	14.9	_	20	
Turn-Off Delay Time	tD(OFF)	_	57.4	_	ns	$V_{DD} = -50V, R_g = 9.1\Omega, I_D = -5A$
Turn-Off Fall Time	t _F	_	34.4	_		
Body Diode Reverse Recovery Time	trr	_	25.2	_	ns	V _G S = 0V, I _S = -5A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{RR}	_	24.5	_	nC	V _G S = 0V, I _S = -5A, dI/dt = 100A/µs

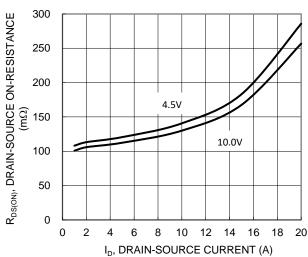
Notes:

Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.



Typical Characteristics - N-CHANNEL





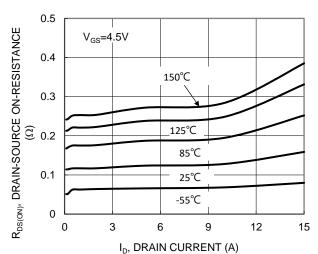


Figure 3. Typical On-Resistance vs. Drain Current

and Gate Voltage

Figure 5. Typical On-Resistance vs. Drain Current and Temperature

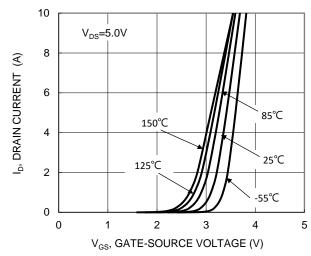


Figure 2. Typical Transfer Characteristic

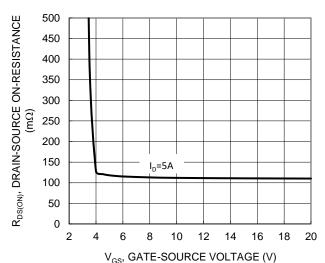


Figure 4. Typical Transfer Characteristic

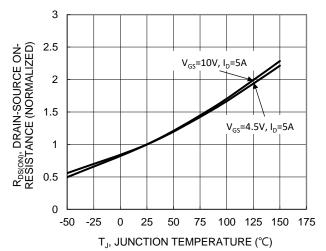


Figure 6. On-Resistance Variation with Temperature



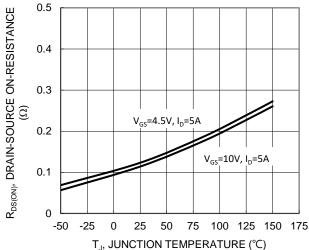


Figure 7. On-Resistance Variation with Temperature

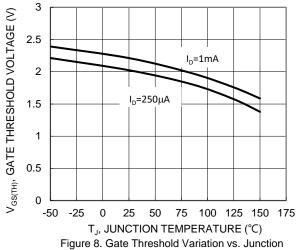


Figure 8. Gate Threshold Variation vs. Junction Temperature

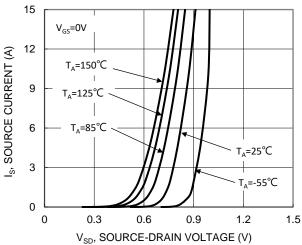


Figure 9. Diode Forward Voltage vs. Current

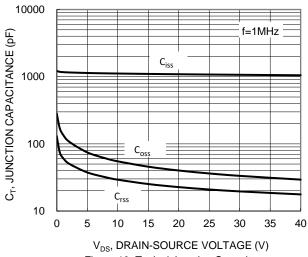
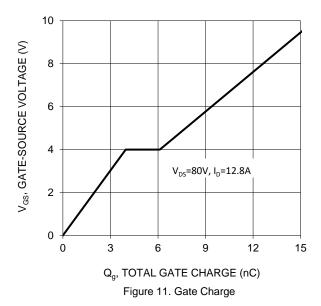
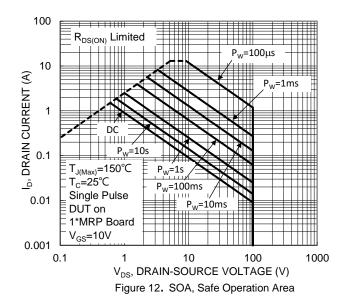


Figure 10. Typical Junction Capacitance







Typical Characteristics - P-CHANNEL

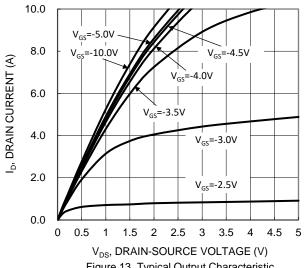


Figure 13. Typical Output Characteristic

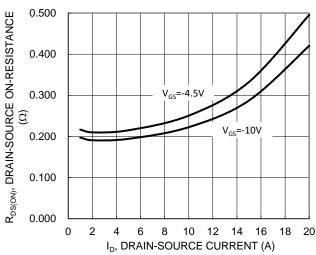


Figure 15. Typical On-Resistance vs. Drain Current and Gate Voltage

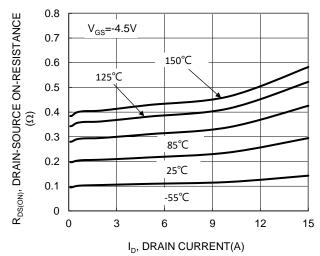


Figure 17. Typical On-Resistance vs. Drain Current and Temperature

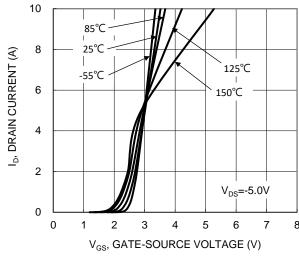


Figure 14. Typical Transfer Characteristic

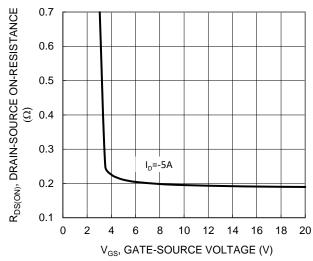


Figure 16. Typical Transfer Characteristic

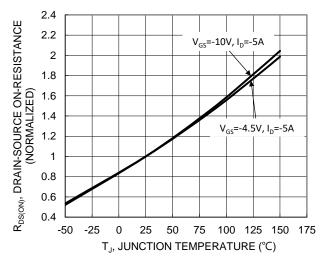
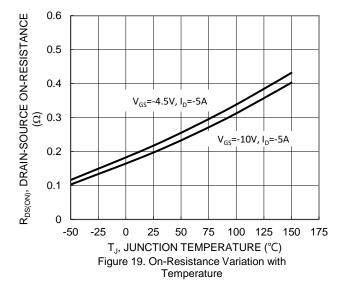
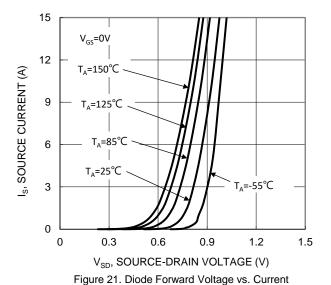


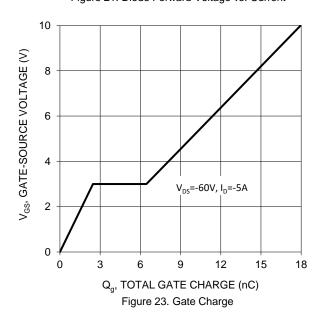
Figure 18. On-Resistance Variation with Temperature

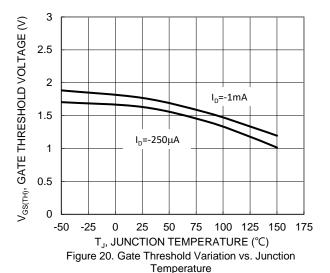


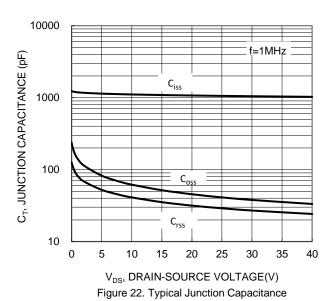


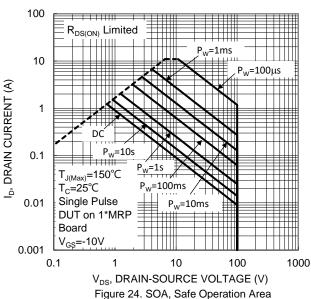




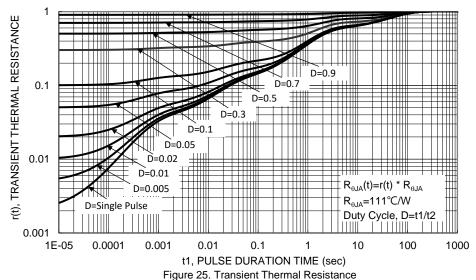










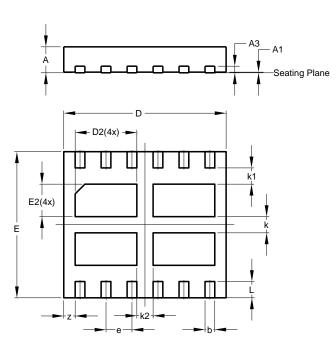




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

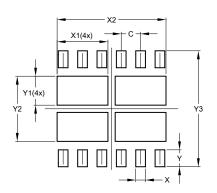
V-DFN5045-12



V-DFN5045-12					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
A3	-	-	0.203		
b	0.25	0.35	0.30		
D	4.95	5.05	5.00		
D2	1.80	2.00	1.90		
Е	4.45	4.55	4.50		
E2	0.90	1.10	1.00		
е	-	-	0.80		
k	-	-	0.50		
k1	-	-	0.50		
k2	-	-	0.50		
L	0.45	0.55	0.50		
Z	-	-	0.35		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



V-DFN5045-12

Dimensions	Value (in mm)
С	0.800
Х	0.400
X1	2.100
X2	4.500
Y	0.700
Y1	1.200
Y2	2.700
Y3	4.800



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